CMOS 8-BIT SINGLE-CHIP MICROCOMPUTER (TLCS-48C)

TMP80C49AP/TMP80C49AP-6 TMP80C39AP/TMP80C39AP-6 TMP80C49AU/TMP80C49AU-6

1. GENERAL DESCRIPTION AND FEATURES

The TMP80C49A is a single chip microcomputer fabricated in Silicon Gate CMOS technology which provides internal 8-bit parallel architecture.

The following basic architectural functions of a computer have been included in a single chip; an 8-bit CPU, 128×8 RAM data memory, 2K×8 ROM program memory, 27 I/O lines and an 8-bit timer/event counter.

The TMP80C49A is particularly efficient as a controller. It has extensive bit handling capability as well as facilities for both binary and BCD arithmetic.

The TMP80C39A/-6 is the equivalent of a TMP80C49A/-6 without ROM program memory on chip. By using this device with external EPROM or RAM, software debugging becomes easy.

The TMP80C49AP/-6 and TMP80C39AP/-6 are in a standard Dual Inline Package. The TMP80C49AU/-6 is in a 44-pin Micro Flat Package.

FEATURES

TMP80C49AP/TMP80C39AP/TMP80C49AU

1.36µs Instruction Cycle Time -40° C to 85°C, 5V $\pm 10\%$

TMP80C49AP-6/TMP80C39AP-6/TMP80C49AU-6

2.5 us Instruction Cycle Time -40° C to 85°C. 5V $\pm 20\%$

- Software Upward Compatible with TMP8049AP/INTEL's 8049
- 2K×8 masked ROM / 128×8 RAM
- Low Power

10mA MAX. in Normal Operation $(V_{CC}=5V, f_{XTAL}=6MHz)$ 10µA MAX. in Power Down Mode $(V_{CC}=5V, f_{XTAL}:DC)$

- Power Down Mode (Stand-by Mode)
- Halt Mode (Idle Mode)

2. PIN CONNECTIONS AND PIN FUNCTIONS

2.1 Pin Connections (Top View)



Figure 2.1 (1) DIP Pin Connections

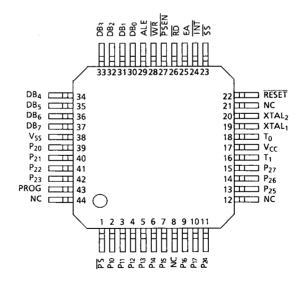


Figure 2.1 (2) Micro Flat Package Pin Connections

2.2 Pin Names And Pin Description

• V_{SS} (Power Supply)

Circuit GND potential

• V_{CC} (Power Supply)

+5V during operation

• \overline{PS} (Input)

The control signal for the power saving at the power down mode (Active Low)

• PROG (Output)

Output strobe for the TMP82C43P I/O expander.

• P₁₀-P₁₇ (Input/Output) Port 1

8-bit quasi-bidirectional port (Internal Pullup $\approx 50 \text{K}\Omega$).

• P₂₀-P₂₇ (Input/Output) Port 2

8-bit quasi-bidirectional port (Internal Pullup $\approx 50 \text{K}\Omega$).

P₂₀-P₂₃ contain the four high order program counter bits during an external program memory fetch and serve as a 4-bit I/O expander bus for the TMP82C43P.

DB₀-DB₇ (Input/Output, Tri-State)

True bidirectional port which can be written or read synchronously using the \overline{RD} , \overline{WR} strobes. The port can also be statically latched. Contains the 8 low order program counter bits during an external program memory fetch, and receives the addressed instruction under the control of \overline{PSEN} .

Also contains the address and data during an external RAM data store instruction, under control of ALE, \overline{RD} , and \overline{WR} .

T₀ (Input/Output)

Input pin testable using the conditional transfer instructions JT0 and JNT0. To can be designated as a clock output using ENT0 CLK instruction.

• T₁ (Input)

Input pin testable using the JT1 and JNT1 instruction. Can be designated the event counter input using the timer/STRT CNT instruction.

• INT (Input)

External interrupt input. Initiates an interrupt if interrupt is enabled. Interrupt is disabled after a reset. Also testable with conditional jump instruction. (Active low)

• RD (Output)

Output strobe activated during a Bus read. Can be used to enable data onto the Bus from an external device. Used as a Read Strobe to External Data Memory (Active Low).

• WR (Output)

Output strobe during a Bus write (Active Low). Used as a Write Strobe to External Data Memory.

• RESET (Input)

Active Low signal which is used to initialize the Processor. Also used during the power down mode.

ALE (Output)

Address Latch Enable. This signal occurs once during each cycle and is useful as a clock output. The negative edge of ALE strobes address into external data and program memory.

PSEN (Output)

Program Store Enable. This output occurs only during a fetch to external program memory (Active Low).

• \overline{SS} (Input)

Single step input can be used in conjunction with ALE to "single step" processor through each instruction when \overline{SS} is low the CPU is placed into a wait state after it has completed the instruction being executed. Also used during the power down mode.

• EA (Input)

External Access input which forces all program memory fetches to reference external memory. Useful for emulation and debug and essential for testing and program verification. (Active High)

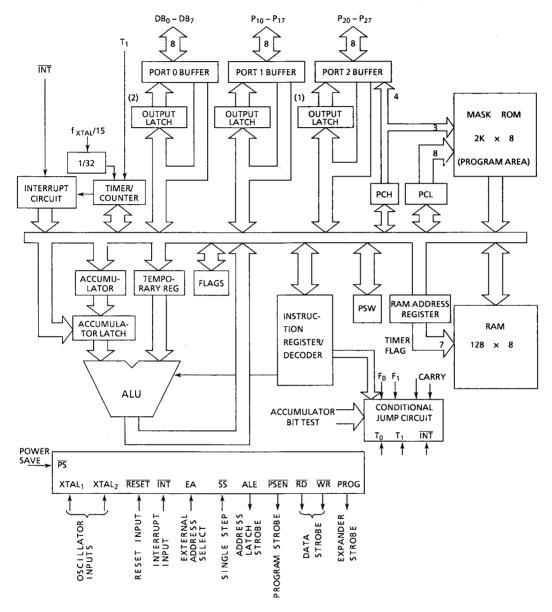
• XTAL 1 (Input)

One side of crystal input for internal oscillator. Also input for external source.

• XTAL 2 (Input)

Other side of crystal input.

2.3 Block Diagram



 $Note \ 1: \qquad The \ lower \ order \ 4 \ bit \ of \ port \ 2 \ output \ latch \ are \ used \ also \ for \ input/output \ operations$

with the I/O expander.

Note 2: The output latch of port 0 is also used for address output.

Figure 2.3 Block Diagram

3. MACHINE INSTRUCTION

The following symbols and codes are used in the list of machine instruction.

Symbol	Meaning
Rr	Working register (0 < r < 7)
Pp	I/O port address P; (0 < p < 7)
JВb	Branch instruction in accordance with bit content (b) of operand
aН	Higher order 3 bits of a
аМ	Medium order 4 bits of a
aL	Lower order 4 bits of a
aML	Medium order or lower order 8 bits of a
(a)	Content of a
[(a)]	Content of RAM addressed by a
EXT[(a)]	Content of external RAM addressed by a
PRO[(a)]	Content of ROM addressed by a
a <m></m>	Value at bit position m of a
a <m:n></m:n>	Value at bit position m to n of a
a←b	Store a into b
a↔b	Exchange a for b
•	Connection
ā	1 complement of a
a+b	a plus b (Addition)
a-b	a minus b (Subtraction)
a∧b	Logical AND for a and b
a∨b	Logical OR for a and b
a∀b	Exclusive OR for a and b
a=b	a is equal to b
a<>b	a is not equal to b
(a) BCD	Converted value of accumulator

List of TLCS-48 Machine Instruction (1/4)

TEM		ssembler	Object ((1st (2nd)	Function		Flag	Cycle
_	Mnemonic		Bin	Hex			C, AC	
	ADD	A , Rr	01101rrr	68+r	(A)+(Rr)	r=0~7	11	1
	ADD	A ,@Rr	0110000r	60+r	(A)←(A)+[(Rr)]	r=0,1	1.7	2
	ADD	A ,#i	00000011	03	(A)←(A)+i		11	2
	[iiiiiiii	ii				
	ADDC	A , Rr	01111rrr	78+r	(A)←(A)+(Rr)+(c)	r=0~7	11	1
	ADDC	Α ,@Rr	0111000r	70+r	(A)←(A)+[(Rr)]+(c)	r=0,1	Į Į	1
	ADDC	A ,#i	00010011	13	(A)←(A)+i+(c)		1 1	2
	1		11111111	ii				
	ANL	A , Rr	01011rrr	58+r	(A)←(A) ∧(Rr)	r=0~7		1
_	ANL	A ,@Rr	0101000r	50+r	(A)←(A) ∧[(Rr)]	r=0,1		1
0	ANL	A ,#i	01010011	53	(A)←(A) ∧i			2
1.	<u> </u>	,	11111111	ii				
2	ORL	A , Rr	01001rrr	48+r	(A)←(A) ∨(Rr)	r=0~7		1
struction	ORL	A ,@Rr	0100000r	40+r	(A)←(A) ∨[(Rr)]	r=0,1		1
st	ORL	A ,#i	01000011	43	(A)←(A) ∨i			2
			11111111	ii				
1	XRL	A , Rr	11011rrr	D8+r	(A)←(A) ∀(Rr)	r=0~7		1
-	XRL	A ,@Rr	1101000r	D0+r	(A)←(A) ∀[(Rr)]	r=0,1		1
ato	XRL	A ,#i	11010011	D3	(A)←(A) ∀i			2
e			iiiiiiiii	ii				
c u m u l	INC	Α	00010111	17	(A)←(A)+1			1
] 5	DEC	Α	00000111	07	(A)←(A)~1			1
Acc	CLR	Α	00100111	27	(A)←0			1
⋖	CPL	Α	00110111	37	(A)←NOT(A)			1
	DA	Α	01010111	57	(A)←(A)BCD		1	1
	SWAP	Α	01000111	47	(A)<7:4> ↔(A)<3:0>			1
	RL	Α	11100111	E7	(A) <n+1> ←(A)<n></n></n+1>			1
					(A)<0> ←(A)<7>	n=0~6		
	RLC	Α	11110111	F7	(A) <n+1> ←(A)<n></n></n+1>		Į.	1
					(C)←(A)<7>			
					(A)<0> ←(C)	n=0~6		<u> </u>
	RR	Α	01110111	77	(A) <n> ←(A)<n+1></n+1></n>	n=0~6		1
					(A)<7> ←(A)<0>			
	RRC	Α	01100111	67	(A) <n> ←(A)<n+1></n+1></n>		1	1
			1		(C)←(A)<0>			
					(A)<7> ←(C)	n=0~6		
	IN	A , Pp	000010pp	08+p	(A)←(Pp)	P=1,2		2
	OUTL	Pp, A	001110рр	38+p	(Pp) ←(A)	P=1,2		
0	ANL	Pp,#i	100110pp	98+p	(Pp) ←(Pp)∧i	P=1,2		2
-			iiiiiiii	ii				
	ORL	Pp,#i	100010pp	88+p	(Pp) ←(Pp)√i	P=1,2		2
	<u></u>		111111111	ii	1			

List of TLCS-48 Machine Instruction (2/4)

TEM	Assembler	Object (1st	:)	Function	Flag	Cycle
-	Mnemonic	Bin	Hex		C, AC	1
	INS A , BUS	00001000	08	(A)←(BUS)		2
	OUTL BUS, A	00000010	02	(BUS)←(AC)		2
	ANL BUS,#i	10011000	98	(BUS)←(BUS) ∧i		2
		11111111	ii			
٦	ORL BUS,#i	10001000	88	(BUS)←(BUS) ∨i		2
<u> </u>		11111111	ii			
_	MOVD A , Pp	000011pp	0C+p	(A)<3:0> ←(Pp) p=4~7 (A)<7:4> ←0		2
1	MOVD Pp, A	001111pp	3C+p	(Pp) ←(A)<3:0> p=4~7		2
	ANLD Pp, A	1001111pp	9C+p	$(Pp) \leftarrow (Pp) \land (A) < 3:0 > p=4~7$		2
	ORLD Pp, A	100011pp	8C+p	(Pp) ←(Pp)√(A)<3:0> p=4~7		2
	INC Rr	00011rrr	18+r	(D-) (/D-) (4		1
(1)	INC @Rr	0001000r	10+r	[(Rr)] +[(Rr)]+1 r=0,1		1
l `''	DEC Rr	11001rrr	C8+r	(Rr) ←(Rr)-1 r=0~7		1
	JMP a	aH00100	aH+4	(PC)<10:0> ←a	-	2
		aML	1	(PC)<11> ←(DBF)		-
	JMPP @A	10110011	B3	(PC)<7:0>←PRO[(PC)<11:8>·(A)]		2
	DJNZ Rr, a	11101rrr	E8+r	(Rr) ←(Rr)-1 r=0~7		2
	100.12 1.11 , 4	aML	2011	if(Rr) ≠0then(PC)<7:0>←aML		-
				else no operation		
	JC a	11110110	F6	if(C)=1 then(PC)<7:0>←aML		2
		aML		else no operation		_
u	JNC a	11100110	E6	if(C)=0 then(PC)<7:0>←aML		2
<u>.</u> ا		aML		else no operation		İ
nstruction	JZ a	11000110	C6	if(A)=0 then(PC)<7:0>←aML		2
1		aML		else no operation		İ
s t	JNZ a	10010110	96	if(A)≠0 then(PC)<7:0>←aML		2
и —		aML		else no operation	Ī	
	JTO a	00110110	36	if T0=1 then(PC)<7:0>←aML		2
l c h		aML		else no operation		
an	JNTO a	00100110	26	if T0=0 then(PC)<7:0>←aML		2
Br		aML		else no operation		
	JT1 a	01010110	56	if T1=1 then(PC)<7:0>←aML		2
		aML		else no operation		}
	JNT1 a	01000110	46	if T1=0 then(PC)<7:0>←aML		2
l		aML		else no operation		
	JFO a	10110110	B6	if F0=1 then(PC)<7:0>←aML		2
		aML		else no operation	<u> </u>	<u> </u>
l	JF1 a	01110110	76	if F1=1 then(PC)<7:0>←aML		2
		aML		else no operation	<u> </u>	<u> </u>
	JTF a	00010110	16	if TF=1 then(PC)<7:0>←aML		2
		aML		else no operation		

^{(1) ·····} Register Instruction

List of TLCS-48 Machine Instruction (3/4)

TEM	Assembler Mnemonic	Object ((1st (2nd)	Function	Flag C, AC	Cycle
-	ivinemonic	Bin	Hex		C, AC	<u></u>
	JNI a	10000110	86	if INT =0 then(PC)<7:0>←aML		2
l		aML		else no operation		
(2)	JBb a	bbb10010	b+12	if (A) =1 then		2
	,	aML		(PC)<7:0>←aML		
				else no operation b=0~7		
1	CALL a	aH10100	aH+14	[(SP)] ←(PSW)<7:4>·(PC)		2
		aML		(SP) ←(SP)+1		
			1	(PC)<10:0> ←a		
				(PC)<11> ←(DBF)		
(3)	RET	10000011	83	(SP)←(SP)−1		2
				(PC) ←[(SP)]<11:0>		
	RETR	10010011	93	(SP)←(SP)-1	11	2
1				(PC) ←[(SP)]<11:0>		
				(PSW)<7:4> ←[(SP)]<15:12>		
	CLR C	10010111	97	(C)←0		1
	CPL C	10100111	A7	(C)←NOT(C)		1
(4)	CLR F0	10000101	85	(F0) ←0		1
` ''	CPL F0	10010101	95	(F0) ←NOT(F0)		
	CLR F1	10100101	A5	(F1) ←0		1
	CPL F1	10110101	B5	(F1) ←NOT(F1)		1
	MOV A , Rr	111111	F8+r	(A)←(Rr) r=0~7		1
	MOV A ,@Rr	1111000r	F0+r	(A)←[(Rr)] r=0,1		2
ļ	MOV A ,#i	00100011	23	(A) ←i		2
		11111111	ii			
_	MOV Rr, A	10101rrr	A8+r	(Rr)←(A) r=0~7		1
ion	MOV @Rr, A	1010000r	A0+r	[(Rr)]←(A) r=0,1		1
t	MOV Rr,#i	10111rrr	B8+r	(Rr)←i r=0~7		2
3		iiiiiiiii	ii			ļ
tru	MOV @Rr,#i	1011000r	B0+r	[(Rr)]←i r=0,1		2
s u		liiiiiiii	ii			ļ
-	MOV A,PSW	11000111	C7	(A) ←(PSW)		1
e ,	MOV PSW,A	11010111	D7	(PSW) ←(A)		1
> 0	XCH A,Rr	00101rrr	28+r	(A) ↔(Rr) r=0~7		1
Σ	XCH A,@Rr	0010000r	20+r	(A) ↔[(Rr)] r=0,1		1
	XCHD A,@Rr	0011000r	30+r	(A)<3:0>→[(Rr)<3:0>] r=0,1		1
	MOVX @Rr,A	1001000r	90+r	EXT[(Rr)] ←(A) r=0,1		1 1
	MOVX A,@Rr	1000000r	80+r	(A) ←EXT[(Rr)] r=0,1	.	
	MOVP A,@A	10100011	A3	(A) ←PRO[(PC)<11:8>·(A)]		1
1	MOVP3 A,@A	11100011	E3	(A) ←PRO[(PC)<11>·011·(A)]		1

^{(2) ·····} Branch Instruction (4) ····· Flag Instruction

^{(3) ·····} Subroutine Instruction

List of TLCS-48 Machine Instruction (4/4)

ITEM		sembler	(2nd) Function		(1st) (2nd)		Function	Flag C, AC	Cycle
			Bin	Hex		C, AC			
	MOV	A,T	01000010	42	(A) ←(TR)		1		
t e	MOV	T,A	01100010	62	(TR)←(A)		1		
0 0 11	STRT	Т	01010101	55	Start Timer		1		
U L	STRT	CNT	01000101	45	Start Counter	••••••	1		
шe	STOP	TCNT	01100101	65	Stop Timer/Counter	*****	1		
; <u> </u>	EN	TCNTI	00100101	25	Enable Timer/Counter Interrupt		1		
L	DIS	TCNTI	00110101	35	Disable Timer/Counter Interrupt		1		
	EN	I	00000101	05	Enable External Interrupt		1		
	DIS	I	00010101	15	Disable External Interrupt		1		
-	SEL	RB0	11000101	C5	(BS)← 0		1		
1	SEL	RB1	11010101	D5	(BS)← 1	***************	1		
<u>۔</u> 0	SEL	MB0	11100101	E5	(DBF) ← 0	•••••	1		
ŭ	SEL	MB1	11110101	F5	(DBF) ← 1	• • • • • • • • • • • • • • • • • • • •	1		
	ENT0	CLK	01110101	75	Enable Clock Output on To		1		
	HALT		00000001	01	Halt	• • • • • • • • • • • • • • • • • • • •	1		
(5)	NOP		00000000	00	no operation		1		

^{(5) ----} Other

TOSHIBA

4. ELECTRICAL CHARACTERISTICS

4.1 Absolute Maximum Ratings

TMP80C49AP/C39AP/C49AU

SYMBOL	ITEM	RATTING
Vcc	V _{CC} Supply Voltage (with respect to GND (VSS))	- 0.5V to + 7V
VINA	Input Voltage (Except EA)	- 0.5V to VCC + 0.5V
VINB	Input Voltage (Only EA)	- 0.5V to + 13V
PD	Power Dissipation (Ta = 85°C)	250mW
TSOLDER	Soldering Temperature (Soldering Time 10 sec)	260°C
T _{STG}	Storage Temperature	- 65°C to 150°C
TOPR	Operating Temperature	- 40°C to 85°C

4.2 DC Characteristics

TMP80C49AP/C39AP/C49AU TOPR = -40° C to 85°C, VCC = +5V ± 10%, V_{SS} = 0V, unless otherwise noted.

SYMBOL	PARAME	TER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
VIL	Input Low Voltage (Except XTAL ₁ , XTAL	-2, RESET)		-0.5	_	0.8	V
VIL1	input Low Voltage (XTAL ₁ , XTAL ₂ , RESE	T)		- 0.5	_	0.6	٧
VIH	Input High Voltage (Except XTAL ₁ , XTAL	₋₂ , RESET, PS)		2.2	_	Vcc	٧
VIH1	Input High Voltage (XTAL ₁ , XTAL ₂ , RESE			0.7x Vcc	_	Vcc	V
VOL	Output Low Voltage (Except P ₁₀ -P ₁₇ , P ₂₀ -	9	IOL = 1.6mA	_	_	0.45	٧
VOL1	Output Low Voltage (P10-P17, P20-P27)	2	IOL = 1.2mA	-	-	0.45	>
VOH11	Output High Voltage (Except P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		IOH = - 1.6mA	2.4	1	_	٧
VOH12	Output High Voltag (Except P ₁₀ -P ₁₇ , P ₂₀ -	е	IOH = -400μA	V _{CC} - 0.8	-		V
VOH21	Output High Voltag (P ₁ 0-P ₁₇ , P ₂₀ -P ₂₇)		IOH = -50μA	2.4	-	_	٧
VOH22	Output High Voltag (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)	e	IOH = - 25μA	V _{CC} - 0.8	-	_	٧
ILI	Input Leak Current (T ₁ , INT, EA, PS)		$V_{SS} \leq V_{IN} \leq V_{CC}$	_	_	± 10	μΑ
ILi1	Input Leak Current (SS, RESET)		$V_{SS} \leq V_{IN} \leq V_C$		-	- 50	μА
ILI2	Output Leak Curren		$V_{SS} + 0.45V \le V_{IN}$ $\le V_{CC}$	_	_	- 500	μА
ILO	Output Leak Curren (High impedace con	t (BUS, T _O) dition)	$V_{SS} + 0.45V \le V_{IN}$ $\le V_{CC}$			± 10	μА
ICC1	V _{CC} Supply	Normal operation	$V_{CC} = 5V$, $f_{XTAL} = 6MHz$	_	_	10	mA
ICCH1	Current	HALT Mode	√ VÌH = V _{CC} − 0.2V VIL = 0.2V	_	_	2.5	IIIA
ICC2	V _{CC} Supply	Normal operation	V _{CC} = 5V, f _{XTAL} = 11MHz		_	15	mA
ICCH2	Current	HALT Mode	VIH = V _{CC} - 0.2V VIL = 0.2V		_	4.0	IIIA

4.3 AC Charactristics

TMP80C49AP/C39AP/C49AU TOPR = -40° C to 85°C, V_{CC} = +5V \pm 10%, V_{SS} = 0V, unless otherwise noted.

		. 33 .	7	1		·
SYMBOL	PARAMETER	TEST CONDITION	f (t)	110	ЛHz	UNIT
				MIN.	MAX.	
t	Clock Period	Note 2	1/xtal f	90.9	1000	ns
t _{LL}	ALE Pulse Width		3.5t – 170	150		ns
t _{AL}	Address Setup Time (ALE)		2t – 110	70	_ `	ns
t _{LA}	Address Hold Time (ALE)	CL = 20pF	t – 40	50	_	ns
t _{CC1}	Control Pulse Width (RD, WR)		7.5t – 200	480	-	ns
t _{CC2}	Control Pulse Width (PSEN)		6t – 200	350	_	ns
t_{DW}	Data Setup Time (WR)		6.5t – 200	390	-	ns
t _{WD}	Data Hold Time (WR)	CL = 20pF	t – 50	40	_	ns
t _{DR}	Data Hold Time (RD, PSEN)	CL = 20pF	1.5t – 30	0	110	ns
t _{RD1}	Data Input Read Time (RD)		5.5t – 120	-	375	ns
t _{RD2}	Data Input Read Time (PSEN)		4t – 120	-	240	ns
t _{AW}	Address Setup Time (WR)		5t – 150	300	_	ns
t _{AD1}	Address Setup Time (RD)		10t - 170	-	730	ns
t _{AD2}	Address Setup Time (PSEN)		7t 170	_	460	ns
t _{AFC1}	Address Float Time (RD, WR)	CL = 20pF	2t – 40	140	_	ns
t _{AFC2}	Address Float Time (PSEN)	CL = 20pF	0.5t - 40	10	-	ns
t _{LAFC1}	ALE to Control Time (RD, WR)		3t – 75	200	-	ns
t _{LAFC2}	ALE to Control Time (PSEN)		1.5t – 75	60	-	ns
t _{CA1}	Control to ALE Time (RD, WR, PROG)		t – 65	25	_	ns
t _{CA2}	Control to ALE Time (PSEN)		4t – 70	290	-	ns

AC Charactristics (Continue) $T_{OPR} = -40^{\circ}\text{C}$ to 85°C, $V_{CC} = +5\text{V} \pm 10\%$, $V_{SS} = 0\text{V}$, unless otherwise noted.

C) (1 4 D O)	DADAMETED	TEST CONDITION	£ (4)	11MHz		UNIT	
SYMBOL	PARAMETER	TEST CONDITION	f (t)	MIN.	MAX.		
t _{CP}	Port Control Setup Time (PROG)		1.5t - 80	50	-	ns	
t _{PC}	Port Control Hold Time (PROG)		4t – 260	100	-	ns	
t _{PR}	Port 2 Input Data Setup Time (PROG)		8.5t – 120		650	ns	
t _{PF}	Port 2 Input Data Hold Time (PROG)		1.5t	0	140	ns	
t _{DP}	Port 2 Output Data Setup Time (PROG)		6t – 290	250	_	ns	
t _{PD}	Port 2 Output Data Hold Time (PROG)		1.5t – 90	40	-	ns	
tpp	PROG Pulse Width		10.5t – 250	700	-	ns	
t _{PL}	Port 2 I/O Data Setup Time (ALE)		4t – 200	160	_	ns	
t _{LP}	Port 2 I/O Data Hold Time (ALE)		0.5t - 30	15		ns	
t _{PV}	Port Output Delay Time (ALE)		4.5t + 100	-	510	ns	
toper	T ₀ Clock Period		3t	270	_	ns	
tcY	Cycle Time		15t	1.36	15.0	μs	

Note: 1. Control Output CL=80pF. BUS Output CL=150pF.

The f(t) assumes 50% duty cycle on XTAL₁ and XTAL₂.
 The Max. Clock frequency is 11MHz. and the Min. Clock frequency is 1MHz.

4.4 Absolute Maximum Ratings

TMP80C49AP-6/TMP80C39AP-6/TMP80C49AU-6

SYMBOL	ITEM	RATTING
Vcc	V _{CC} Supply Voltage (with respect to GND (V _{SS}))	-0.5V to +7V
VINA	Input Voltage (Except EA)	-0.5V to VCC + 0.5V
V _{INB}	Input Voltage (Only EA)	- 0.5V to + 13V
P _D	Power Dissipation (Ta = 85°C)	250mW
T _{SOLDER}	Soldering Temperature (Soldering Time 10 sec)	260°C
T _{STG}	Storage Temperature	− 65°C to 150°C
T _{OPR}	Operating Temperature	- 40°C to 85°C

4.5 DC Characteristics (I)

TMP80C49AP-6/TMP80C39AP-6/TMP80C49AU-6 TOPR = -40° C to 85°C, V_{CC} = +5V ± 10%, V_{SS} = 0V, unless otherwise noted

SYMBOL	PARAMI	TER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
VIL	Input Low Voltage			-0.5	-	0.8	V
VIH	Input High Voltage (Except XTAL ₁ , XTA			2.2	_	Vcc	V
VIH1	Input High Voltage (XTAL ₁ , XTAL ₂ , RES			0.7 x V _{CC}	_	Vcc	V
VOL	Output Low Voltag (Except P ₁₀ -P ₁₇ , P ₂₀	e -P ₂₇)	IOL = 1.6mA	-	_	0.45	٧
VOL1	Output Low Voltag (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)	e	IOL = 1.2mA	-	_	0.45	V
VOH11	Output High Voltage (Except P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		IOH = - 1.6mA	2.4	_	_	٧
VOH12	Output High Voltag (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)	Output High Voltage (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		V _{CC} -0.8	_		٧
VOH21	Output High Voltag (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)	je	IOH = - 50μA	2.4	_	_	٧
VOH22	Output High Voltag (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)	e	IOH = - 25μA	V _{CC} -0.8	_	_	٧
ILI	Input Leak Current (T ₁ , INT, EA, PS)		$V_{SS} \leq V_{IN} \leq V_{CC}$	_	_	± 10	μА
ILI1	Input Leak Current (SS, RESET)		$V_{SS} \le V_{IN} \le V_{CC}$	-		- 50	μΑ
ILI2	Input Leak Current (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		$V_{SS} + 0.45V \le V_{IN}$ $\le V_{CC}$	-	_	- 500	μΑ
ILO	Output Leak Current (BUS, T ₀) (High impedance condition)		$\begin{array}{l} V_{SS} + 0.45 V \leq V_{IN} \\ \leq V_{CC} \end{array}$	-	-	± 10	μА
ICC1	V _{CC} Supply Normal operation		$V_{CC} = 5V$, $f_{XTAL} = 6MHz$	_	_	10	mA
ICCH1	Current	HALT Mode	VIH = V _{CC} - 0.2V VIL = 0.2V	_	_	2.5	1167

4.6 DC Characteristics (II)

TMP80C49AP-6/TMP80C39AP-6/TMP80C49AU-6 TOPR = -40° C to 85°C, V_{CC} = +5V ± 20%, V_{SS} = 0V, unless otherwise noted

SYMBOL	PARAMET	ER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
VIL	Input Low Voltage			- 0.5	_	0.15 x V _{CC}	V
VIH	Input High Voltage (Except XTAL ₁ , XTAL ₂	, RESET, PS)		0.5 x V _{CC}	_	Vcc	V
VIH1	Input High Voltage (XTAL ₁ , XTAL ₂ , RESET	, PS)		0.7 x V _{CC}	_	Vcc	٧
NO L	Output Low Voltage (Except P ₁₀ -P ₁₇ , P ₂₀ -P	27)	IOL = 1.6mA	_	+	0.45	>
VOL1	Output Low Voltage (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)	IOL = 1.2mA	_	_	0.45	>	
VOH12	Output High Voltage (Except P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		IOH = -400μA	V _{CC} – 0.8	_	_	>
VOH22	Output High Voltage (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		IOH = - 25μA	V _{CC} – 0.8	_	-	>
ILI	input Leak Current (T1, INT, EA, PS)		V _{SS} ≤ VIN≤ V _{CC}	_	_	± 10	μА
ILi1	Input Leak Current (SS, RESET)		$V_{SS} \le VIN \le V_{CC}$	_	_	- V _{CC}	μА
ILI2	Input Leak Current (P ₁₀ -P ₁₇ , P ₂₀ -P ₂₇)		$V_{SS} + 0.45V \le VIN$ $\le V_{CC}$	-	_	- V _{CC}	μА
ILO	Output Leak Current (BUS, T ₀) (High impedance condition)		$V_{SS} + 0.45V \le VIN$ $\le V_{CC}$	_	_	± 10	μA
ICC1	V 6	Normal operation	$V_{CC} = 5V$, $f_{XTAL} = 6MHz$	_	_	10	mA
ICCH1	V _{CC} Supply Current	HALT Mode	VIH = V _{CC} - 0.2V VIL = 0.2V		_	2.5	

4.7 AC Charactristics

TMP80C49AP-6/TMP80C39AP-6/TMP80C49AU-6 TOPR = -40° C to 85°C, V_{CC} = +5V ± 20%, V_{SS} = 0V, unless otherwise noted.

SEMBOL	PARAMETER	TEST	£ (4)	6 MHz		UNIT	
SEIVIBUL	PARAMETER	CONDITION	f (t)	MIN.	MAX.	UNII	
t	Clock Period	Note 2	1 / xtal f	166.6	1000	ns	
t _{LL}	ALE Pulse Width		3.5t – 170	410	_	ns	
t _{AL}	Address Setup Time (ALE)		2t – 110	220	_	ns	
t _{LA}	Address Hold Time (ALE)	CL = 20pF	t – 40	120	_	ns	
t _{CC1}	Control Pulse Width (RD,WR)		7.5t – 200	1050	_	ns	
t _{CC2}	Control Pulse Width (PSEN)		6t – 200	800	_	ns	
t _{DW}	Data Setup Time (WR)		6.5t – 200	880	-	ns	
t _{WD}	Data Hold Time (WR)	CL = 20pF	t – 50	120	-	ns	
t _{DR}	Data Hold Time (RD,PSEN)	CL = 20pF	1.5t – 30	0	220	ns	
t _{RD1}	Data Input Read Time (RD)		5.5t – 120	_	880	ns	
t _{RD2}	Data Input Read Time (PSEN)		4t – 120	_	550	ns	
t _{AW}	Address Setup Time (WR)		5t – 150	680	_	ns	
t _{AD1}	Address Setup Time (RD)		10t – 170	_	1500	ns	
t _{AD2}	Address Setup Time (PSEN)		7t – 170	_	1000	ns	
t _{AFC1}	Address Float Time (RD, WR))	CL = 20pF	2t - 40	290	-	ns	
t _{AFC2}	Address Float Time (PSEN)	CL = 20pF	0.5t - 40	40		ns	
t _{LAFC1}	ALE to Control Time (RD,WR)		3t – 75	420	_	ns	
t _{LAFC2}	ALE to Control Time (PSEN)		1.5t – 75	175	_	ns	
t _{CA1}	Control to ALE Time (RD,WR,PROG)		t – 65	100	_	ns	
t _{CA2}	Control to ALE Time (PSEN)		4t – 70	590	_	ns	

AC Charactristics (Continue) $T_{OPR} = -40^{\circ}\text{C}$ to 85°C, $V_{CC} = +5\text{V} \pm 10\%$, $V_{SS} = 0\text{V}$, unless otherwise noted.

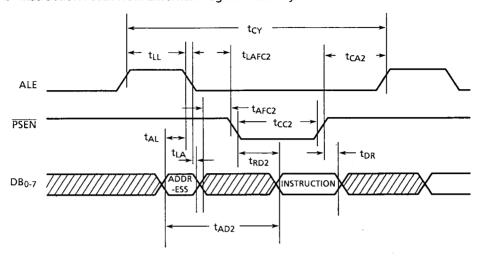
SYMBOL	PARAMETER	TEST CONDITION	£ (4)	111	ЛHz	UNIT	
STIVIBUL	PARAIVIETER	LESI CONDITION	f (t)	MIN.	MAX.	0.411	
t _{CP}	Port Control Setup Time (PROG)		1.5t - 80	170	-	ns	
t _{PC}	Port Control Hold Time (PROG)		4t – 260	400	-	ns	
t _{PR}	Port 2 Input Data Setup Time (PROG)		8.5t – 120	-	1290	ns	
tpF	Port 2 Input Data Hold Time (PROG)		1.5t	0	250	ns	
t _{DP}	Port 2 Output Data Setup Time (PROG)	·	6t – 290	710	_	ns	
tP _D	Port 2 Output Data Hold Time (PROG)		1.5t – 90	160	_	ns	
tpp	PROG Pulse Width		10.5t – 250	1500	-	ns	
t _{PL}	Port 2 I/O Data Setup Time (ALE)		4t – 200	460	_	ns	
t _{LP}	Port 2 I/O Data Hold Time (ALE)		0.5t - 30	130	-	ns	
t _{PV}	Port Output Delay Time (ALE)		4.5t + 100	_	850	ns	
toprr	T ₀ Clock Period		3t	500	-	ns	
t _{CY}	Cycle Time		15t	2.5	15.0	μs	

- Note : 1. Control Output CL = 80pF. BUS Output CL = 150pF.
 - 2. The f(t) assumes 50% duty cycle on XTAL1 and XTAL2.

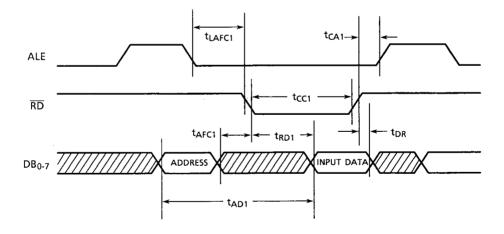
The Max. Clock frequency is 6MHz. and the Min. Clock frequency is 1MHz.

4.8 Timing Waveform

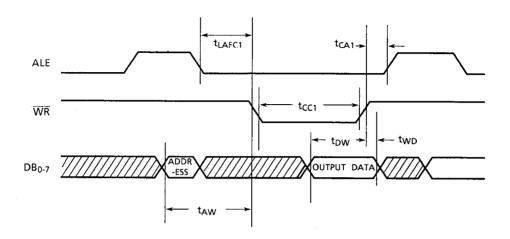
A. Instruction Fetch from External Program Memory



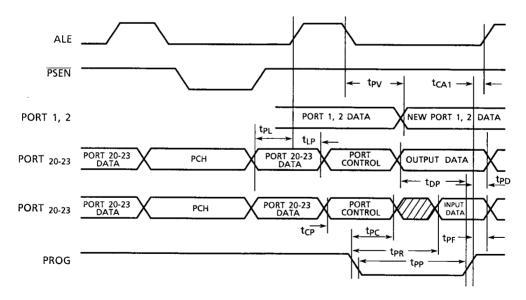
B. Read from External Data Memory



C. Write into External Data Memotry



D. Timing of Port 2 during Expandar Instruction Execution



4.9 Stand-By Function

4.9.1 PoweR Down Mode (I) Data Hold Mode in RAM

The operation of oscillation circuit is suspended by setting \overline{PS} terminal to low level after \overline{RESET} terminal has been set to low level. Consequently, all the data in RAM area can be held in low power consumption.

The minimum hold voltage of VCC in this mode is 2V.

 \overline{PS} terminal is set to high level to resume oscillation after V_{CC} has been reset to 5V, and then \overline{RESET} terminal is set to high level, thus, the normal mode is restarted from the initialize operation (address 0).

(1) DC Characteristics

TMP80C49AP/C39AP/C49AU TMP80C49AP-6/C39AP-6/C49AU-6

: $T_{OPR} = -40^{\circ}C$ to $85^{\circ}C$, $V_{SS} = 0V$

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VSB1	Standby Voltage (1)		2.0		6.0	٧
ISB1	Standby Current (1)	V _{CC} = 5V, VIH = V _{CC} - 0.2V, VIL = 0.2V	_	0.5	10	μА

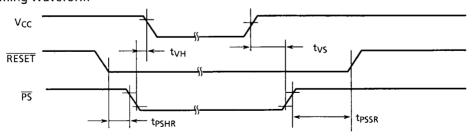
(2) AC Characteristics

TMP80C49AP/C39AP/C49AU TMP80C49AP-6/C39AP-6/C50AU-6 : $V_{CC} = +5V \pm 10\%$, $V_{SS} = 0V$: $V_{CC} = +5V \pm 20\%$, $V_{SS} = 0V$

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
tpshr	Power Save Hold Time (RESET)		10	_	_	μς
tpssr	Power Save Setup Time (RESET)		10	_	_	ms
t∨H	V _{CC} Hold Time (PS)		5	_	_	μs
tvs	V _{CC} Setup Time (PS)		5	_	_	μs

Note: $t_{CY} = 2.5 \mu s (f_{XTAL} = 6MHz)$

(3) Timing Waveform



4.9.2 Power Down Mode (II) ALL Data Hold Mode

The operation of oscillation circuit is suspended by setting \overline{PS} terminal to low level after \overline{SS} terminal has been set to low level. Consequently, all data can be held in low power consumption.

The minimum hold voltage of V_{CC} in this mode is 3V.

 \overline{PS} terminal is set to high level to resume oscillation after V_{CC} has been reset to 5V, and then \overline{SS} terminal is set to high level, thus, the normal mode is restarted continuously from the state just before the power down mode (II).

(1) AC Characteristics

TMP80C49AP/C39AP/C49AU TMP80C49AP-6/C39AP-6/C49AU-6

 $: T_{OPR} = -40^{\circ}C \text{ to } 85^{\circ}C, V_{SS} = 0V$

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VSB ₂	Standby Voltage (2)		3.0	_	6.0	٧
ISB ₂	Standby Current (2)	V _{CC} = 5V, VIH = V _{CC} - 0.2V, VIL = 0.2V		0.5	10	μΑ

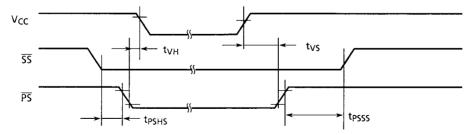
(2) AC Characteristics

TMP80C49AP/C39AP/C49AU TMP80C49AP-6/C39AP-6/C49AU-6 : $V_{CC} = +5V \pm 10\%$, $V_{SS} = 0V$: $V_{CC} = +5V \pm 20\%$, $V_{SS} = 0V$

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
t _{PSHR}	Power Save Hold Time (SS)		10	<u> </u>	_	μs
tpssr	Power Save Setup Time (SS)		10	_	_	ms
tvH	V _{CC} Hold Time (PS)		5	_	_	μs
t _{VS}	V _{CC} Setup Time (PS)		5	_	_	μs

Note: $t_{CY} = 2.5 \mu s (f_{XTAL} = 6MHz)$

(3) Timing Waveform



4.9.3 HALT MODE

(1) HALT INSTRUCTION

OP code is "01H". HALT INSTRUCTION is an additional instruction to the standard 8048/8049 instruction set.

(2) Entry to HALT MODE

On the execution of HALT INSTRUCTION, TMP80C49A/TMP80C39A enter HALT MODE.

(3) Status in HALT MODE

The oscillator continues its operation, however, the internal clocks and internal logic values just prior to the execution of HALT INSTRUCTION are maintained. Power consumption in HALT MODE is less than 50% of normal operation. The status of each pins are described in the following table.

(4) Release from HALT MODE

HALT MODE is released by either of two signals (RESET, INT).

- (4.1) RESET Release Mode: An active RESET input signal causes the normal reset function. TMP80C49A/TMP80C39A start the program at address "000H".
- (4.2) INT Release Mode : An active INT input signal causes the normal operation.
 - In case of interrupt enable mode (EI MODE), TMP80C49A/TMP80C39A execute the interrupt service routine, after the execution of one instruction which is located at the next address after HALT INSTRUCTION.
 - In case of interrupt disable mode (DI MODE), TMP80C49A/TMP80C39A execute normal operation from the next address after HALT INSTRUCTION.

(5) Supply Voltage Range in HALT MODE

The operating supply voltage range and the operating temperature range are same as in normal operation.

TMP80C49AP/C39AP/C49AU : $V_{CC} = 5V \pm 10\%$ TMP80C49AP-6/C39AP-6/C49AU-6 : $V_{CC} = 5V \pm 20\%$

4.9.4 Pin Status In Power Down Mode (I) (II)

PIN NAME	STATUS			
DB ₀ ~DB ₇				
P ₁₀ ~P ₁₇	☐ High impedance ☐ Input disabled			
P ₂₀ ~P ₂₇				
Т0	High impedance, input disabled			
T ₁	Input disabled			
XTAL ₁	High impedance			
XTAL ₂	Output "High" Level			
RESET, SS	Input disabled when oscillator is stopped. Pull-up transistors turn off.			
ĪNT, EA	Input disabled when oscilltor is stopped.			
RD, WR, ALE PROG, PSEN	High impedance			

4.9.5 Pin Status In HALT MODE

PIN NAME	STATUS
DB ₀ ~DB ₇	
P ₁₀ ~P ₁₇	Values prior to the execution of HALT INSTRUCTION are maintained.
P ₂₀ ~P ₂₇	
Т0	Status prior to the execution of HALT INSTRUCTION is maintained.
T ₁	Input disabled
XTAL ₁ , XTAL ₂	Continue oscillation
RESET, INT	Input enabled
SS, EA	Input disabled
RD, WR PROG, PSEN	Output "High" level
ALE	Output "Low" level

5. **OSCILLATOR**

QUARTZ CRYSTAL

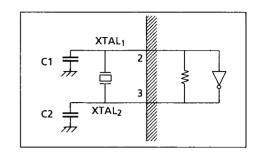
f = 1MHz to 4MHz : C1 = C2 = 30pF

f = 4MHz to 11MHz : C1 = C2 = 20pF

CERAMIC RESONATOR

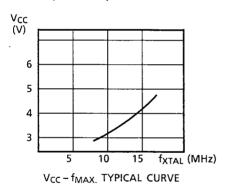
f = 1MHz to 3MHz: C1 = C2 = 100pF

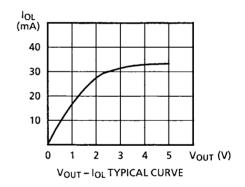
f = 3MHz to 11MHz : C1 = C2 = 30PF

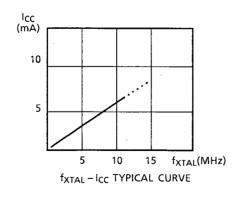


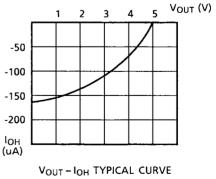
TYPICAL CHARACTERISTICS 6.

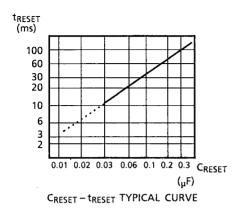
: Vcc = 5V,Ta = 25°C, unless Otherwise noted.

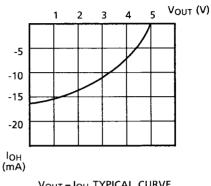










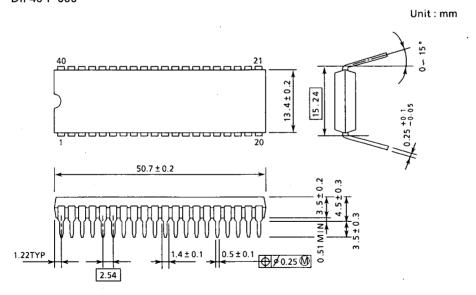


V_{OUT} – I_{OH} TYPICAL CURVE (DB, CONTROL)

7. OUTLINE DRAWING

7.1 Outline Drawing For TMP80C49AP/-6,TMP80C39AP/-6 (DIP: Dual Inline Package)

DIP40-P-600



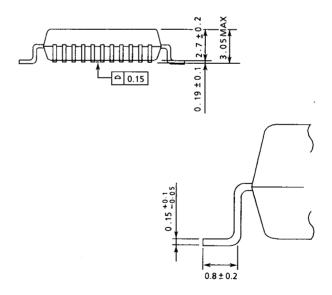
Note: 1. This dimension is measured at the center of bending point of leads.

2. Each lead pitch is 2.54mm, and all the leads are located within ± 0.25 mm from their theoritical positions with respect to No.1 and No.40 leads.

7.2 Outline Drawing For TMP80C49AU/-6 (Micro Flat Package)

QFP44-P-1010A

13.8 ± 0.3 10.0 ± 0.2 33 23 24 22 27 80 90 10.0 ± 0.2 10 Unit: mm



Note: 1. The above dimensions don't include the burr of package and the residue of tie-bar cut.

The burr of package and the residure of tie-bar cut should be 0.15 mm (Max.).

2. Applied ti the lead flat porttion.